

ABSTRACT OF THE DISCLOSURE

A semiconductor device comprising a semiconductor element and a support member having a recess for housing the semiconductor element is disclosed. The support member includes lead electrodes and a support part holding the lead electrodes so that a surface of tip portions of the lead electrodes are exposed in a bottom of the recess. A main surface of the support member has at least a first main surface disposed adjacent to the recess and a second main surface disposed adjacent to the first main surface. The second main surface preferably has a protrusion and a further recess. The protrusion preferably forms an outer wall around a depression. The semiconductor device having this configuration has excellent and accurate positioning and can be strongly bonded with other members. The semiconductor device can also be obtained with a high process yield.